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1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and procedure with terminals crimped on the specified maximum size wire

2. APPLICABLE STANDARDS:

Methods for test of connectors for electronic equipment

MIL - STD - 202 MIL - STD - 1344 Test methods for electrical connectors

3. APPLICABLE SERIES NO: CI08 SERIES

(Header: P/N:CI08****HR*-NH)

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C.BOARD

6.1 Thickness: 1.6mm(.063")

6.2 P.C. Board Layout: See attached drawings



REVIEWED: David APPROVED: Eisley VERIFIED: Hank .



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7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		3A 200V AC (r.m.s.)
			(AWG#26)
			2.5A 200V AC (r.m.s.)
			(AWG#28)
			1.5A 200V AC (r.m.s.)
			(AWG#30)
7.2	Contact resistance	Dry circuit of DC 20 mV max., 10 mA max.(EIA-364-23)	Less than 25 m Ω
7.3	Dielectric strength	When applied AC 500 V 1 minute between adjacent terminal(EIA-364-20)	No discharge, flashover or breakdown
			Current leakage: 1mA Max.
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground (EIA-364-21)	More than $1000 \text{ M}\Omega$

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Mating & Un-mating force	Insert and withdraw connector at speed of 25 ± 3 mm per minute	See Item 11
8.2	Pin retention force	Push pin from insulator base at speed 25 ± 3 mm per minute More than 0.5 Kg	
8.3	Durability	The sample should be mounted on the tester and fully mated and unmated 60 cycles specified at the rate of 25.4±3mm/min.(EIA-364-09)	Contact resistance: To pass Para 7.2

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Temperature rise	Mate connector: measure the temperature rise at rated current. The ambient condition is still air at 25°C (UL 498)	The temperature rise above ambient shall not exceed 30°C
9.2	Vibration	The electrical load condition shall be 100mA max. for all contacts. 1.5 mm 10-55-10 HZ / minute each 2 hours for X, Y and Z directions	Appearance: No damage Discontinuity: 1 micro second max.
		(EIA-364-28)	



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	ITEM	TEST CONDITION	REQUIREMENT
9.3	Shock(Mechanical)	Subject mated connectors to 50G's (peak value) half-sine shock pulses of 11 milliseconds duration. Three shock in each direction shall be applied along the three mutually perpendicular axes of the test specimen (18 shocks). The electrical load condition shall be 100mA maximum for all contacts.	Discontinuity: 1 micro second max.
9.4	Solder ability	DIP Type Lead-Free Process:	Minimum:
		Soldering time: 3 ± 0.5 second	90% of immersed area
		Soldering pot: 245 ± 5°C	
		SMT Type Lead-Free Process:	
		Subject the test area of contacts into the flux for 5~10Sec. And then into solder bath.	
		Soldering time: 3 ± 0.5 second	
		Soldering temperature: 245 ± 5°C (EIA-364-52)	
9.5	Resistance to soldering	DIP Type Lead-Free Process	No damage
	heat	Soldering time: 5 ± 0.5 second	
		Soldering pot: 260 ± 5°C	
		SMT Type Lead-Free Process:	
		Soldering time: 20 second Max.	
		Soldering pot: 250~260°C	
		Refer Reflow temperature profile(12.2)	
9.6	Hand Soldering Method	Use a soldering iron that has a sufficient head capacity and high stability of temperature. The tip of the iron should be shaped so as not to touch the part body directly. Temperature: 380±10°C 3s	No damage



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	ITEM	TEST CONDITION	REQUIREMENT
9.7	Heat aging	85± 2°C, 96 hours(EIA-364-17)	Appearance: No damage
			Contact resistance:
			To pass Para 7.2
			Dielectric strength:
			To pass Para 7.3
			Insulation resistance:
			To pass Para 7.4
9.8	Cold aging	-40 ± 2°C , 96 hours	Appearance: No damage
			Contact resistance:
			To pass Para 7.2
9.9	Humidity	40°C, 90-95% RH, 96 hours	Appearance: No damage
		measurement must be taken within 30 min.	Contact resistance:
		after tested (EIA-364-31)	To pass Para 7.2
			Dielectric strength:
			To pass Para 7.3
			Insulation resistance:
			To pass Para 7.4
9.10	Temperature cycling	Five cycle consists of :(EIA-364-32)	Appearance: No damage
		$(1)-40 {}^{+0}_{-3} {}^{\circ}\text{C}$, 30 min.	Contact resistance:
		(2)Room temp. 10-15 min.	To pass Para 7.2
		$(3)85 + 3 \circ C$, 30 min.	Dielectric strength:
		(4)Room temp. 10-15 min.	To pass Para 7.3
			Insulation resistance:
			To pass Para 7.4
9.11	Salt spray	Temperature: 35 ± 2°C	Appearance: No damage
		Solution: 5 ± 1%	Contact resistance:
		Spray time:	To pass Para 7.2
		Gold flash: 8 hours	
		Measurement must be taken after water	
		rinse	

10. AMBIENT TEMPERATURE RANGE: -40 to + 85°C



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11. Mating and Un-mating Force:

PIN No.	Mating((kgf) max.)	Un-mating((kfg)min.)	60th Un-mating((kfg)min.)
2	2.00	0.30	0.20
3	2.00	0.30	0.20
4	2.00	0.30	0.20
5	2.50	0.40	0.30
6	2.50	0.40	0.30
7	3.00	0.50	0.40
8	3.00	0.50	0.40
9	3.50	0.60	0.50
10	3.50	0.60	0.50
11	4.00	0.70	0.60
12	4.00	0.70	0.60

12. Recommended IR Reflow Temperature Profile:

12.1 Using Lead-Free Solder Paste

